**Customer Product Specification Sheet**

**BB02-BE**: 1.27 mm X 1.27 mm (0.05" X 0.05") Box Header, Through Hole, Dual Row, Straight - 10 to 100 Contacts

**Specifications**:
- **Current Rating**: 1 AMP
- **Insulator Resistance**: 1000 Megohms Min.
- **Dielectric Withstanding**: AC 300 V
- **Contact Resistance**: 20m Ohms Max.
- **Operating Temperature**: -40°C to +105°C
- **Contact Material**: Phosphor Bronze
- **Insulator Material**: Thermoplastic, UL 94V-0
- **Plating**: Gold, Tin, or Selective over 30-50u" Nickel
- **Solderability**: IR Reflow: 280°C for 10 sec; Wave: 250°C for 5-10 sec; Manual Solder: 380°C for 3-5 sec

**Packaged in Tray or Tube**.

**Mates With**
- Perfect mating parts: BB02-CM, BB02-CU
- Other mating parts: BB02-CL, BB02-CN (4.40mm profile only)

**Notes**:
1. **Mating Heights**:
   - a. With insulation height of A=5.7MM, the mating height is 1.5MM+Socket Height.
   - b. With insulation height of B=7.3MM, the mating height is 3.2MM+Socket Height.

**Recommended PCB Board SMD Layout**

**How to Order**

```
BB02 - BEXX1 - XXX - X000000
```

**Number of Contacts**: 10 to 98

**Contact Plating Options**:
- K = Gold Flash (Standard)
- A = 10u" Gold on Contact/Gold Flash on Tail
- B = 15u" Gold on Contact/Gold Flash on Tail
- C = 30u" Gold on Contact/Gold Flash on Tail
- T = Bright Tin
- M = Matt Tin
- D = Gold Flash on Contact/Bright Tin on Tail
- E = 10u" Gold on Contact/Bright Tin on Tail
- F = 15u" Gold on Contact/Bright Tin on Tail
- G = 30u" Gold on Contact/Bright Tin on Tail

**H Height Options**:
- A = 5.70MM
- B = 7.30MM

**Locating Peg Options**:
- A = With Peg
- B = Without Peg

**Scale**: 1:1
**Third Angle**: Not to Scale
**Material**: See Note

**Type**: BB02-BE

**Drawing Number**: BB02-BE

**Drawing Information**
- **Drawing**: B83
- **Title**: BOX HEADER
- **Sheet**: 1 of 1
- **Date**: 21 JUN 17
- **Revision**: 2.0
- **Units**: mm

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